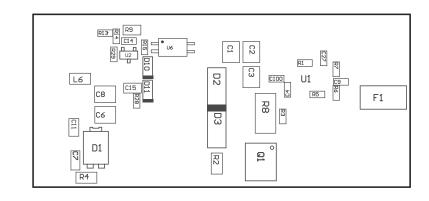


COMPONENTS MARKED 'DNP' SHOULD NOT BE POPULATED. ASSEMBLY VARIANT: 001

| PCB VIEWED FROM TOP SIDE | BOARD #: PMP10856 | REV: A | SUN REV | : Not In VersionControl |
|----------------------------------|--------------------|---------------|---------|-------------------------|
| | | | | |
| PLOT NAME = Top Assembly Drawing | GENERATED : 1/6/20 | 015 8: 39: 32 | AM | TEXAS INSTRUMENTS |



COMPONENTS MARKED 'DNP' SHOULD NOT BE POPULATED. ASSEMBLY VARIANT: 001

| PCB VIEWED FROM BOTTOM SIDE | BOARD #: PMP10856 | REV: A | SUN REV | : Not In VersionControl |
|-------------------------------------|--------------------|---------------|---------|-------------------------|
| | | | | |
| PLOT NAME = Bottom Assembly Drawing | GENERATED : 1/6/20 | 015 8: 39: 33 | AM | TEXAS INSTRUMENTS |

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